

Title (en)

METHOD OF PRODUCTION OF HIGH PURITY SILVER PARTICLES

Title (de)

VERFAHREN ZUR HERSTELLUNG HOCHREINER SILBERTEILCHEN

Title (fr)

PROCEDE DE PRODUCTION DE PARTICULES D'ARGENT DE HAUTE PURETE

Publication

EP 1819467 A4 20100120 (EN)

Application

EP 05851218 A 20051013

Priority

- US 2005036727 W 20051013
- US 61887604 P 20041014

Abstract (en)

[origin: WO2006049831A1] A method for synthesizing high purity silver particles and colloids without requiring the addition of either surfactants or reducing agents thereto, or requiring only a minimal amount thereof. The synthesizing process comprises: (i) a silver oxalate synthesizing process; (ii) a process of dispersing silver oxalate into an appropriate carrier; and {iii) a process of heating said silver oxalate dispersed into said carrier at a temperature of at least 100°C. Silver particles and colloids of various form factor and size may be synthesized depending upon the reaction conditions, the carrier, and the type of surfactant.

IPC 8 full level

B22F 9/20 (2006.01)

CPC (source: EP KR US)

B22F 9/16 (2013.01 - KR); **B22F 9/18** (2013.01 - KR); **B22F 9/20** (2013.01 - KR); **B22F 9/30** (2013.01 - EP US); **B22F 2998/10** (2013.01 - EP US); **B22F 2999/00** (2013.01 - EP US)

Citation (search report)

- [XY] US 2426761 A 19470902 - ADRIEN CAMBRON, et al
- [Y] EP 1201301 A1 20020502 - MITSUBISHI CHEM CORP [JP]
- [Y] US 2004055420 A1 20040325 - GARBAR ARKADY [IL], et al
- [A] US 6660058 B1 20031209 - OH SEONG-GEUN [KR], et al
- See references of WO 2006049831A1

Citation (examination)

- US 6114553 A 20000905 - KIRIKI MASAHIRO [JP], et al
- JP S491153 B1 19740111

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